

## Final Product/Process Change Notification Document #: FPCN21371X

Issue Date: 22 June 2016

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Title of Change:	Qualification of Advanced Semiconductor Engineering (ASE), located in Shanghai, China for assembly of				
Title of Change.	devices AMIS49587C5872G and AMIS49587C5872RG.				
Proposed first ship date:	29 September 2016 <i>or earlier after customer approval</i>				
Troposed mist simp date.	25 September 2010 of currier after customer approval				
Contact information:	Contact your local ON Semiconductor Sales Office or <thelma.hammer@onsemi.com></thelma.hammer@onsemi.com>				
Samples:	Contact your local ON Semiconductor Sales Office or <john.wollen@onsemi.com></john.wollen@onsemi.com>				
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <andy.esteva@onsemi.com></andy.esteva@onsemi.com>				
	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior				
	to implementation of the change.				
Type of notification:					
	ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of				
	delivery of this notice. To do so, contact <pcn.support@onsemi.com>.</pcn.support@onsemi.com>				
Change Part Identification:	Affected products will be identified with assembly site code in the marking along with the date code.				
Change category:	☐ Wafer Fab Change ☐ Assembly Change ☐ Test Change ☐ Other				
Change Sub-Category(s):		☐ Datasheet/Product Doc change			
	'Addition Material Change	☐ Shipping/Packaging/Marking			
	Product specific change	_			
Manufacturing Process Char		☐ Other:			
Sites Affected:					
☐ All site(s) ☐ not ap	oplicable ON Semiconductor site(s):				
		Advanced Semiconductor Engineering			
		Shanghai			
Description and Purpose:					
This is a Final Change Matification to appropriate Advanced G. 1. 1. 5. 1. 1. (ASS) 1. 1. 1. Ch. 1.					
This is a Final Change Notification to announce that Advanced Semiconductor Engineering (ASE) located in Shanghai, China has been					
successfully qualified as an assembly source for the affected devices below. There is no impact on the electrical performance of the affected devices. This will allow additional manufacturing conscitu and flexibility. Upon the expiration of this EDCN, assembly of the affected devices will					
devices. This will allow additional manufacturing capacity and flexibility. Upon the expiration of this FPCN, assembly of the affected devices will					

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be produced in either of the two locations, ASE Shanghai or Unisem, Batam.

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**Reliability Data Summary:** 

**QV Device Name:** 20241-010-XTD

Report ID: NQFP\_AS\_A01 Package: QFN 52 8X8

Test	Specification	Condition	Interval	Results
HTOL	JESD22-A108	Ta=125°C, 100 % max rated Vcc	1000 hrs	0/240
HTSL	JESD22-A103	Ta= 125°C	1008 hrs	0/77
TC	JESD22-A104	Ta= -65°C to +150°C	500 cyc	0/231
HAST	JESD22-A110	110°C, 85% RH, 18.8psig, bias	264 hrs	0/231
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231
PC	J-STD-020 JESD-A113	MSL 3 @ 260 °C		
SD	JSTD002	Ta = 245C, 10 sec		0/45

## **Electrical Characteristic Summary:**

Electrical characteristics are not impacted.

## **List of Affected Standard Parts:**

Part Number	Qualification Vehicle	
AMIS49587C5872G	20241-010-XTD	
AMIS49587C5872RG	20241-010-XTD	

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